



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE4976-2K		<b>Issued</b>		28. August 2013		
<b>MA#</b>		MA000505228						
<b>Package</b>		PG-SC59-3-4		<b>Weight*</b>		13.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.705	5.08	5.08	50755	50755
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		76	
	non noble metal	titanium	7440-32-6	0.005	0.04		378	
	non noble metal	chromium	7440-47-3	0.016	0.11		1134	
	non noble metal	copper	7440-50-8	5.224	37.63	37.79	376322	377910
wire	noble metal	gold	7440-57-5	0.011	0.08	0.08	825	825
encapsulation	organic material	carbon black	1333-86-4	0.056	0.40		4032	
	plastics	brominated resin	-	0.070	0.50		5039	
	inorganic material	antimonytrioxide	1309-64-4	0.140	1.01		10079	
	plastics	epoxy resin	-	1.273	9.17		91718	
	inorganic material	silicondioxide	60676-86-0	5.457	39.31	50.39	393076	503944
leadfinish	non noble metal	tin	7440-31-5	0.240	1.73	1.73	17277	17277
plating	noble metal	silver	7440-22-4	0.363	2.62	2.62	26177	26177
glue	plastics	epoxy resin	-	0.056	0.40		4045	
	noble metal	silver	7440-22-4	0.265	1.91	2.31	19067	23112
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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